

Patent Abstracts of Japan

PUBLICATION NUMBER : 61287254
PUBLICATION DATE : 17-12-86

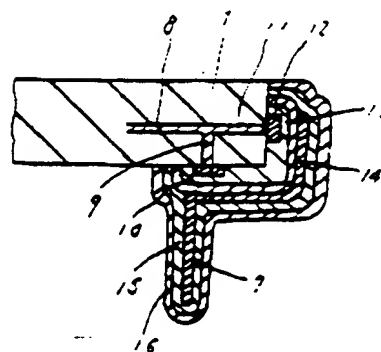
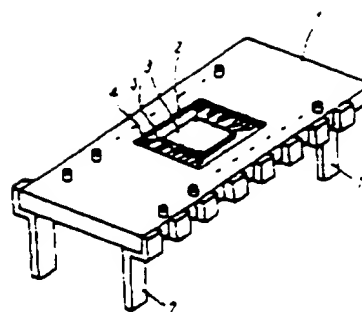
APPLICATION DATE : 14-06-85
APPLICATION NUMBER : 60128203

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INT.CL. : H01L 25/04 H01L 23/48

TITLE : SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To improve the connecting strength and the reliability by providing a plurality of connecting points of internal wirings with a lead terminal in a package substrate.
CONSTITUTION: A package substrate 1 is composed of a multilayer wiring ceramic substrate, a semiconductor chip 3 is contained in a cavity 2, and connected by wirings 5 with a terminal 4. Internal wirings 8, 11 are formed of W-metallized layer, and the internal wirings 9 are formed of through hole wirings of W-metallized layer. The end of the wirings 9 is connected with the W-metallized layer 10 on the bottom of the substrate 1 to connect the wirings 11 with the W-metallized layer 12 of the side of the substrate 1, a lead terminal 7 is bonded through Ni-plating film 13 and an Au-plating film 14, an Ni-plating film 15 and an Au-plating film 16 are again superposed, and coated to complete it.

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